

Title (en)

Method and apparatus for forming a molding

Title (de)

Verfahren und Vorrichtung zur Herstellung eines Formteiles

Title (fr)

Procédé et appareil pour le formage d'une pièce

Publication

**EP 0904914 A3 20000216 (EN)**

Application

**EP 98108066 A 19980504**

Priority

JP 27978097 A 19970925

Abstract (en)

[origin: EP0904914A2] A method and an apparatus for molding a molding with a shape changing area Mc at a predetermined portion 61 of an extruded strip 60 where the shape of a designing side of the predetermined portion changes comprises a bottom face removal step of removing a bottom face 67 of a predetermined portion 65 of said extruded strip 60 to have a shape and a depth corresponding to those of said shape changing area to form a bottom face removal portion; a heating/softening step of heating/softening a bottom face removal portion 68 of said extruded strip 60; a stamping step of stamping said bottom face removal portion 68 of said extruded strip 60 by a stamping die 80 having a die face corresponding to said shape changing area so that it is shaped in said die shape. <IMAGE>

IPC 1-7

**B29C 43/38**; **B29C 37/00**

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

- [A] FR 2503023 A1 19821008 - ESSILOR INT [FR]
- [A] DE 3802396 A1 19890803 - TOKIWA CHEM IND LTD [JP]
- [XY] PATENT ABSTRACTS OF JAPAN vol. 1997, no. 03 31 March 1997 (1997-03-31)
- [XY] PATENT ABSTRACTS OF JAPAN vol. 1996, no. 12 26 December 1996 (1996-12-26)
- [XY] PATENT ABSTRACTS OF JAPAN vol. 018, no. 538 (M - 1686) 13 October 1994 (1994-10-13)

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